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In the Claims:

1. (Currently Amended) A semiconductor IC (integrated circuit) chip, A semiconductor IC (integrated circuit) chip, A structure for providing a bond area and a probe area on a semiconductor chip, comprising:
- a metal line;
- an interconnect formed through a dielectric layer connecting to the metal line;
- a bond pad on said semiconductor chip having a first portion disposed over the metal line and the interconnect, and a second portion disposed over the dielectric layer and offset from the metal line;
- the first portion including a bond area for providing an attachment point for a connection; and
- the second portion including a probe area for providing contact with a probe, wherein the bond area is separated from the probe area.
2. (Currently Amended) The semiconductor [[IC]] chip as recited in claim 1, wherein the metal line includes copper.
3. (Currently Amended) The semiconductor [[IC]] chip as recited in claim 1, wherein the bond pad includes aluminum.
4. (Currently Amended) The semiconductor [[IC]] chip as recited in claim 1, further comprising a barrier layer disposed between the interconnect and the metal line to prevent diffusion therebetween.